

IN THE CLAIMS:

A status of all the claims of the present Application is presented below:

1. (Currently amended) An electronic circuit assembly test apparatus, comprising:
a support member having a plurality of probes, each probe adapted to contact a corresponding test area of an electronic circuit assembly; and
a probe assembly coupled to the support member to enable lateral movement of the probe assembly relative to the support member, the probe assembly having a plurality of probes configured to contact test areas of the electronic circuit assembly different than the test areas contacted by the probes of the support member, wherein a spacing density of the probes of the probe assembly is greater than a spacing density of the probes of the support member.
2. (Original) The apparatus of Claim 1, wherein the spacing density of the probes of the probe assembly corresponds to test areas of an integrated circuit.
3. (Currently amended) The apparatus of Claim 1, wherein the probe assembly is ~~adapted to move~~ laterally movable relative to the support member in at least two different directions.
4. (Original) The apparatus of Claim 1, wherein the probe assembly comprises at least one alignment guide adapted to cooperate with an alignment guide disposed on the electronic circuit assembly.
5. (Original) The apparatus of Claim 1, wherein the probe assembly comprises at least one limiter adapted to limit movement of the probes of the probe assembly toward the electronic circuit assembly.
6. (Original) The apparatus of Claim 1, wherein the probe assembly is movably coupled to the support member to provide non-lateral movement of the probe assembly relative to the support member.
7. (Original) The apparatus of Claim 1, wherein the probes of the probe assembly comprise spring-biased probes.

8. (Original) The apparatus of Claim 1, further comprising at least one spring disposed between the probe assembly and the support member.

9. (Currently amended) An electronic circuit assembly test apparatus, comprising:
first probe means coupled to a support member and adapted to contact corresponding test areas on an electronic circuit assembly;

support means movably coupled to the support member; and

second probe means coupled to the support means and configured to contact test areas on the electronic circuit assembly different than the test areas contacted by the first probe means, the second probe means having a spacing density of probes greater than a spacing density of probes of the first probe means.

10. (Currently amended) The apparatus of Claim 9, wherein the support means is movably coupled to the support member to enable non-lateral movement of the support means relative to the support member.

11. (Original) The apparatus of Claim 9, wherein the support means is coupled to the support member to enable lateral movement of the support means relative to the support member.

12. (Original) The apparatus of Claim 9, further comprising means for aligning the second probe means with corresponding test areas of the electronic circuit assembly.

13. (Original) The apparatus of Claim 9, further comprising means for limiting travel of the second probe means toward the electronic circuit assembly.

14-27. (Canceled)

28. (Currently amended) An electronic circuit assembly test apparatus, comprising:
a support member having a plurality of probes configured to contact a first plurality of test areas of an electronic circuit assembly; and

a probe assembly having a probe assembly support movably coupled to the support member, the probe assembly having a plurality of probes coupled to the probe assembly support and configured to contact a second plurality of test areas of the electronic circuit assembly, wherein the probes of the probe assembly are spaced to accommodate a spacing density of the second plurality of test areas greater than a spacing density of the first plurality of test areas.

29. (Currently amended) The apparatus of Claim 28, wherein the probe assembly support is adapted to move laterally relative to the support member.

30. (Previously presented) The apparatus of Claim 28, wherein the probe assembly comprises at least one alignment guide adapted to cooperate with an alignment guide disposed on the electronic circuit assembly.

31. (Previously presented) The apparatus of Claim 28, wherein the probe assembly comprises at least one limiter adapted to limit movement of the probes of the probe assembly toward the electronic circuit assembly.

32. (Currently amended) The apparatus of Claim 28, wherein the probe assembly support is movably coupled to the support member to provide non-lateral movement of the probe assembly relative to the support member

33. (Previously presented) The apparatus of Claim 28, further comprising at least one spring disposed between the probe assembly and the support member